

5.0mm x 6.0mm FULL-COLOR SURFACE MOUNT LED LAMP

PRELIMINARY SPEC



ATTENTION OBSERVE PRECAUTIONS FOR HANDLING **ELECTROSTATIC** DISCHARGE SENSITIVE **DEVICES**

Part Number: AAA5060SURZGQBFC

Hyper Red Green Blue

Features

- Chips can be controlled separately.
- Suitable for all SMT assembly and solder process.
- Available on tape and reel.
- Package: 500pcs / reel.
- Moisture sensitivity level : level 4.
- RoHS compliant.

Description

The Hyper Red source color devices are made with AlGaInP on GaAs substrate Light Emitting Diode.

The Green source color devices are made with InGaN on Sapphire Light Emitting Diode.

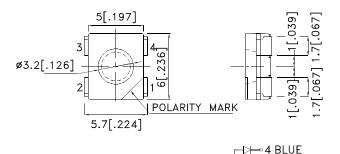
The Blue source color devices are made with InGaN Light Emitting Diode.

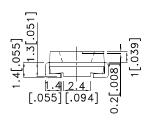
Static electricity and surge damage the LEDS.

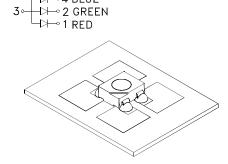
It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.

All devices, equipment and machinery must be electrically grounded.

Package Dimensions







- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.25(0.01") unless otherwise noted.
- 3. Specifications are subject to change without notice.4. The device has a single mounting surface. The device must be mounted according to the specifications.





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Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) [2] @ 50mA *30mA		Viewing Angle [1]
			Min.	Тур.	201/2
AAA5060SURZGQBFC	Hyper Red (AlGaInP)		380	500	100°
	Green (InGaN)	WATER CLEAR	*280	*650	
	Blue (InGaN)		*180	*400	

- 1. 01/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value. 2. *Luminous intensity with asterisk is measured at 30mA; Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device Typ.		Max.	Units	Test Conditions	
λpeak	Peak Wavelength	Hyper Red Green Blue	650 515 461		nm	IF=20mA	
λD [1]	Dominant Wavelength	Hyper Red Green Blue	630 525 465		nm	IF=20mA	
Δλ1/2	Spectral Line Half-width	Hyper Red Green Blue	27 30 25		nm	IF=20mA	
С	Capacitance	Hyper Red Green Blue	45 45 100		pF	Vr=0V;f=1MHz	
VF [2]	Forward Voltage	Hyper Red Green Blue	1.9 3.3 3.3	2.5 4.1 4	V	IF=20mA	
lR	Reverse Current	Hyper Red Green Blue		10 10 10	uA	V _R =5V	

Notes:

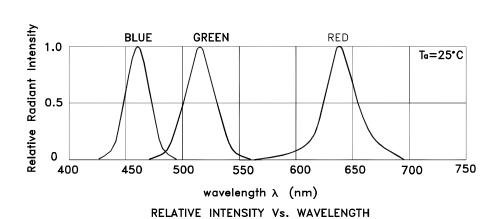
- 1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

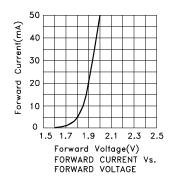
Parameter	Hyper Red	Green	Blue	Units		
Power dissipation[2]		mW				
DC Forward Current	50	30	30	mA		
Peak Forward Current [1]	185	150	150	mA		
Reverse Voltage		V				
Operating Temperature	-40°C To +85°C					
Storage Temperature	-40°C To +85°C					

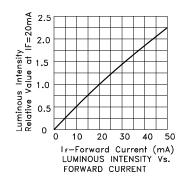
- Notes: 1. 1/10 Duty Cycle, 0.1ms Pulse Width. 2. Within 350mW at all chips are lightened.

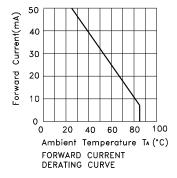
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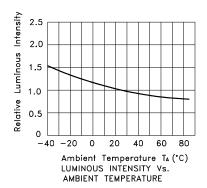


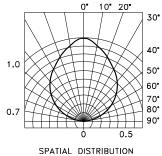
AAA5060SURZGQBFC Hyper Red







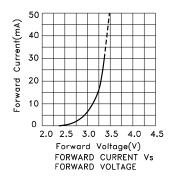


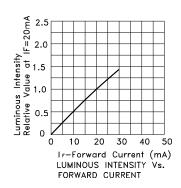


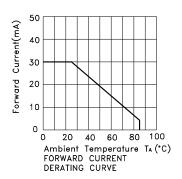
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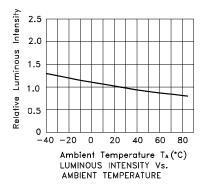
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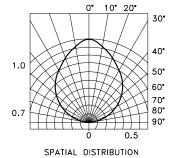
Green







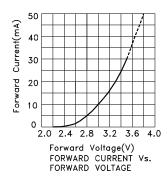


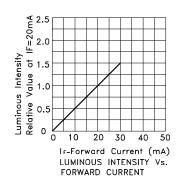


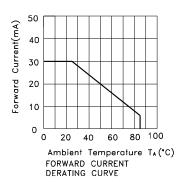
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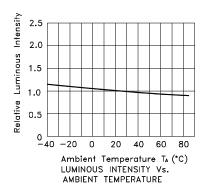
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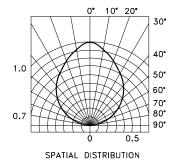
Blue











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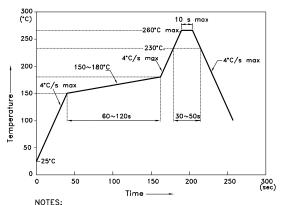
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AAA5060SURZGQBFC

Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



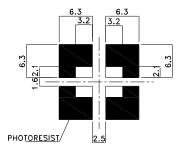
- NOTES:

 1.We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.

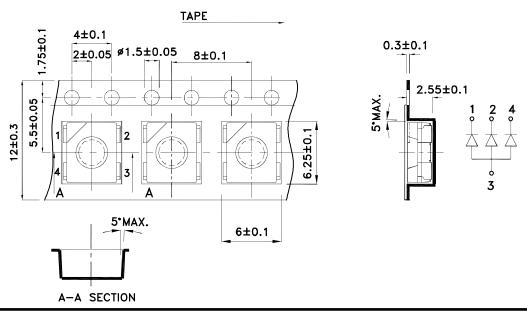
 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.

 3.Number of reflow process shall be 2 times or less.

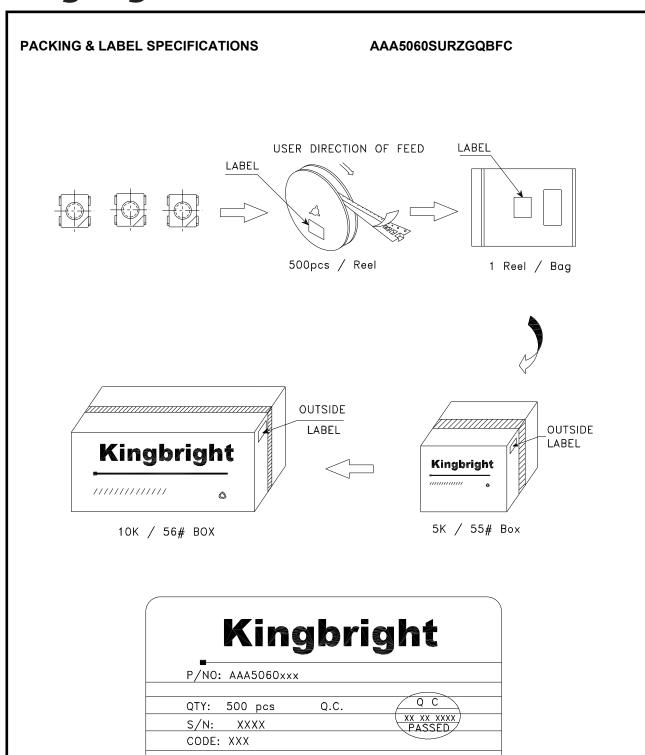
Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



Tape Dimensions (Units: mm)



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LOT NO:

DATE: OCT/29/2009 DRAWN: M.L.Xu

RoHS Compliant

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